Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!

Contact us

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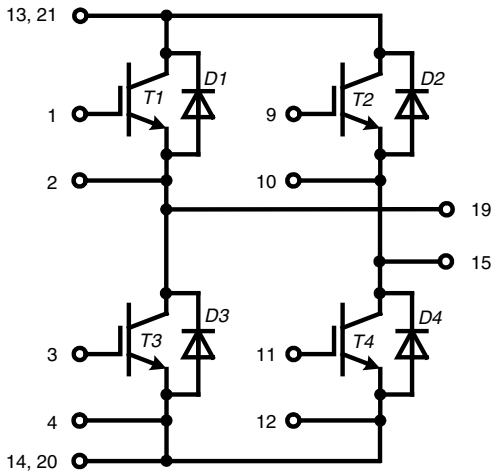
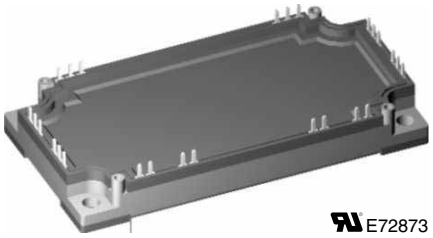
IGBT Module
H Bridge

V_{CES} = 1200 V
I_{C25} = 183 A
$V_{CE(sat)}$ = 1.8 V

Part name (Marking on product)

MIEB101H1200EH





Features:

- SPT+ IGBT technology
- low saturation voltage
- low switching losses
- square RBSOA, no latch up
- high short circuit capability
- positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- SONIC™ free wheeling diode
  - fast and soft reverse recovery
  - low operation forward voltage
- solderable pins for PCB mounting
- package with copper base plate

Application:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies

Package:

- "E3-Pack" standard outline
- Insulated copper base plate
- Soldering pins for PCB mounting

Ouput Inverter T1 - T4

Symbol	Definitions	Conditions		min.	Ratings typ.	max.	Unit
V_{CES}	*collector emitter voltage*		T_{VJ} = 25°C			1200	V
V_{GES}	*max. DC gate voltage*	continuous				±20	V
V_{GEM}	*max. transient collector gate voltage*	transient				±30	V
I_{C25}	*collector current*		T_C = 25°C			183	A
I_{C80}			T_C = 80°C			128	A
P_{tot}	*total power dissipation*		T_C = 25°C			630	W
$V_{CE(sat)}$	*collector emitter saturation voltage*	I_C = 100 A; V_{GE} = 15 V	T_{VJ} = 25°C		1.8	2.2	V
	(on chip level) ①		T_{VJ} = 125°C		2.0	2.4	V
$V_{GE(th)}$	*gate emitter threshold voltage*	I_C = 4 mA; V_{GE} = V_{CE}	T_{VJ} = 25°C	5	6	7	V
I_{CES}	*collector emitter leakage current*	V_{CE} = V_{CES}; V_{GE} = 0 V	T_{VJ} = 25°C			0.3	mA
			T_{VJ} = 125°C		0.9	3	mA
I_{GES}	*gate emitter leakage current*	V_{GE} = ±20 V				200	nA
C_{ies}	*input capacitance*	V_{CE} = 25 V; V_{GE} = 0 V; f = 1 MHz			7430		pF
$Q_{G(on)}$	*total gate charge*	V_{CE} = 600 V; V_{GE} = 15 V; I_C = 100 A			750		nC
$t_{d(on)}$	*turn-on delay time*	inductive load V_{CE} = 600 V; I_C = 100 A V_{GE} = ±15 V; R_G = 10 Ω L_S = 70 nH	T_{VJ} = 125°C		120		ns
t_r	*current rise time*				55		ns
$t_{d(off)}$	*turn-off delay time*				460		ns
t_f	*current fall time*				240		ns
E_{on}	*turn-on energy per pulse*				9.5		mJ
E_{off}	*turn-off energy per pulse*				9.7		mJ
$E_{rec(off)}$	*reverse recovery losses at turn-off*				4.2		mJ
RBSOA	*reverse bias safe operating area*	V_{GE} = ±15 V; R_G = 10 Ω;	T_{VJ} = 125°C V_{CEK} = 1200 V			200	A
SCSOA	*short circuit safe operating area*						
t_{SC}	*short circuit duration*	V_{CE} = 900 V; V_{GE} = ±10 V;	T_{VJ} = 125°C			10	µs
	short circuit current	R_G = 3.9 Ω; non-repetitive					
R_{thJC}	*thermal resistance junction to case*	(per IGBT)				0.2	K/W

Output Inverter D1 - D4

Symbol	Definitions	Conditions		min.	Ratings typ.	max.	Unit
V_{RRM}	*max. repetitve reverse voltage*		T_{VJ} = 25°C			1200	V
I_{F25}	*forward current*		T_C = 25°C			135	A
I_{F80}			T_C = 80°C			90	A
V_F	*forward voltage*	I_F = 100 A; V_{GE} = 0 V	T_{VJ} = 25°C		2.00	2.20	V
	(on chip level) ①		T_{VJ} = 125°C		1.95	2.25	V
I_{rr}	*max. reverse recovery current*	inductive load			120		A
t_{rr}	*reverse recovery time*	V_{CE} = 600 V; I_C = 100 A			330		ns
Q_{rr}		V_{GE} = ±15 V; R_G = 10 Ω	T_{VJ} = 125°C		12.5		µC
E_{rec}		L_S = 70 nH			4.2		mJ
R_{thJC}	*thermal resistance junction to case*	(per diode)				0.4	K/W

T_C = 25°C unless otherwise stated

Module

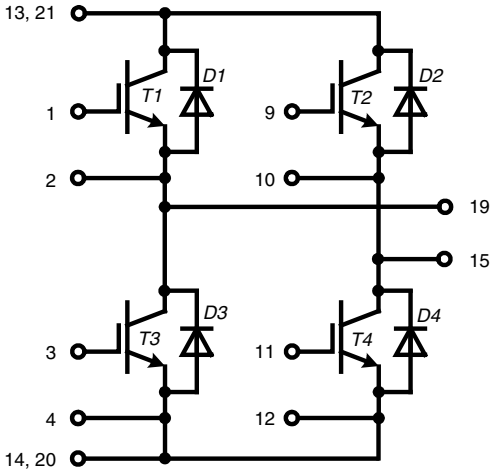
Symbol	Definitions	Conditions		Ratings min.	typ.	max.	Unit
T_{VJ}	*operating temperature*			-40		125	°C
T_{VJM}	*max. virtual junction temperature*					150	°C
T_{stg}	*storage temperature*			-40		125	°C
V_{ISOL}	*isolation voltage*	$I_{ISOL} \leq$ 1 mA; 50/60 Hz	t = 1 min			3000	V~
			t = 1 s			3600	V~
CTI	*comparative tracking index*					200	
M_d	*mounting torque (M5)*			3		6	Nm
$R_{pin\ to\ chip}$	*see* ①				1.8		mΩ
d_S	*creep distance on surface*			12.7			mm
d_A	*strike distance through air*			9.6			mm
R_{thCH}	*thermal resistance case to heatsink*	with heatsink compound			0.1		K/W
Weight					300		g

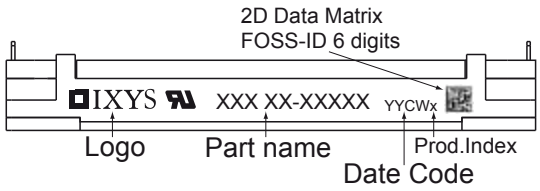
① $V_{CE} = V_{CE(sat)} + 2x\ R_{pin\ to\ chip} \cdot I_C$

T_C = 25°C unless otherwise stated

Curves are measured on modul level except Fig. 14 to Fig. 17

Circuit Diagram



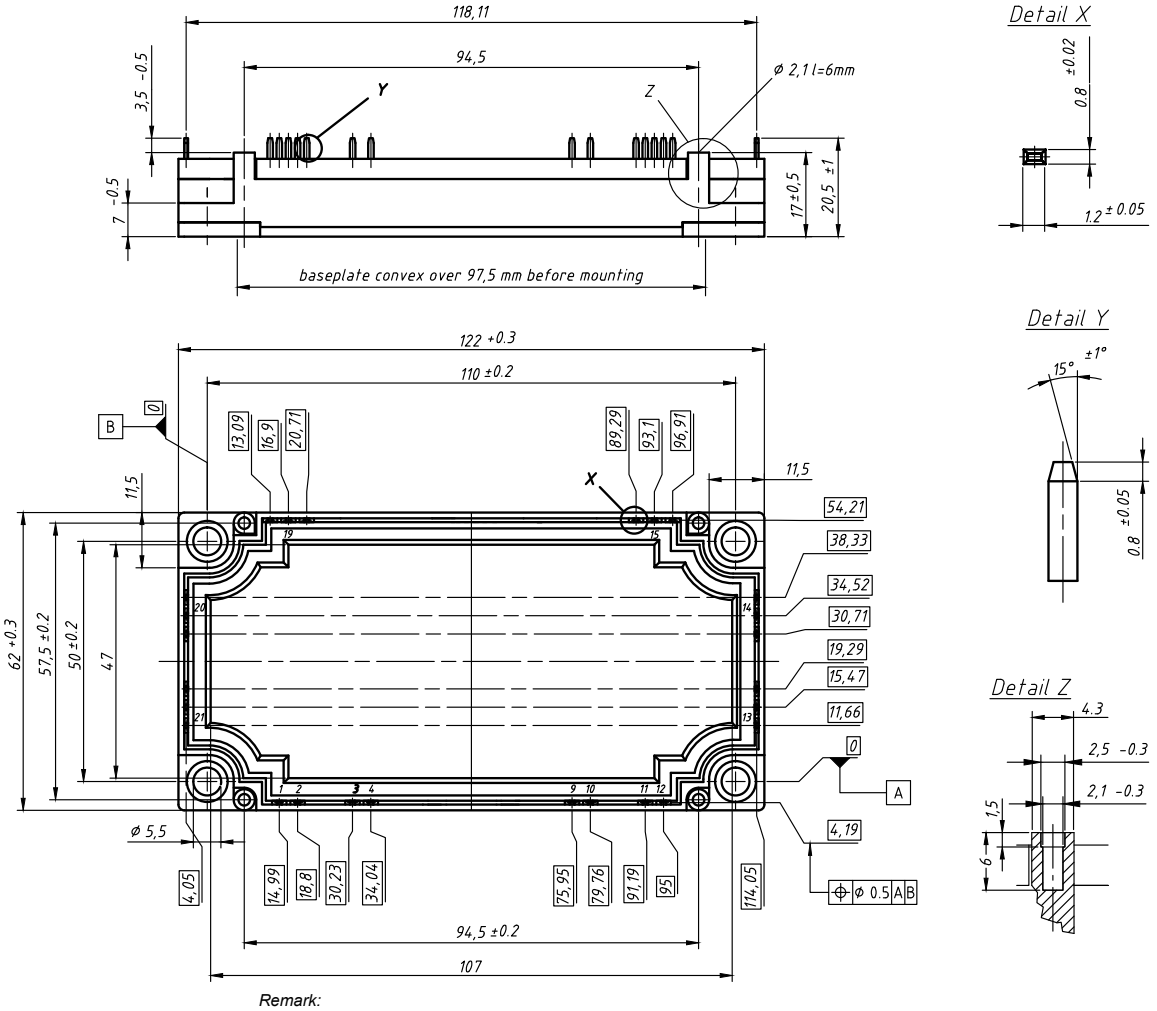


Part number

M = Module
I = IGBT
E = SPT
B = 2nd Generation
101 = Current Rating [A]
H = H~ Bridge
1200 = Reverse Voltage [V]
EH = E3-Pack

Outline Drawing

Dimensions in mm (1 mm = 0.0394“)



Remark:
Dimensions without tolerances acc. DIN ISO 2768-T1-m

Product Marking

Ordering	Part Name	Marking on Product	Delivering Mode	Base Qty	Ordering Code
Standard	MIEB101H1200EH	MIEB101H1200EH	Box	5	510534

IXYS reserves the right to change limits, test conditions and dimensions.

20110615a

Transistor T1 - T4

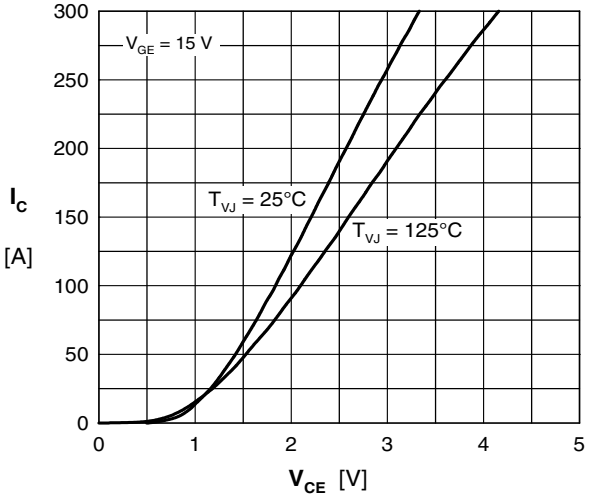


Fig. 1 Typ. output characteristics

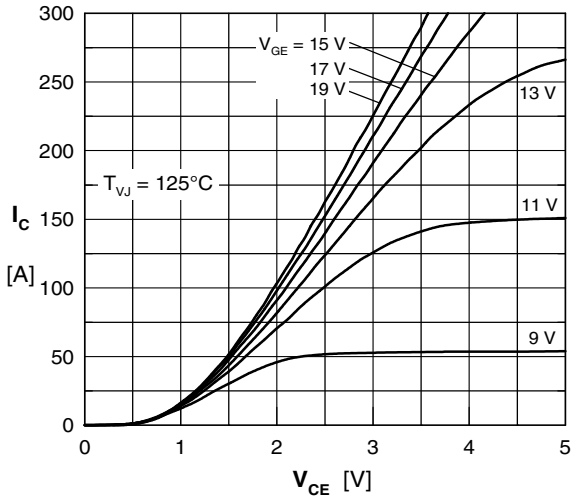


Fig. 2 Typ. output characteristics

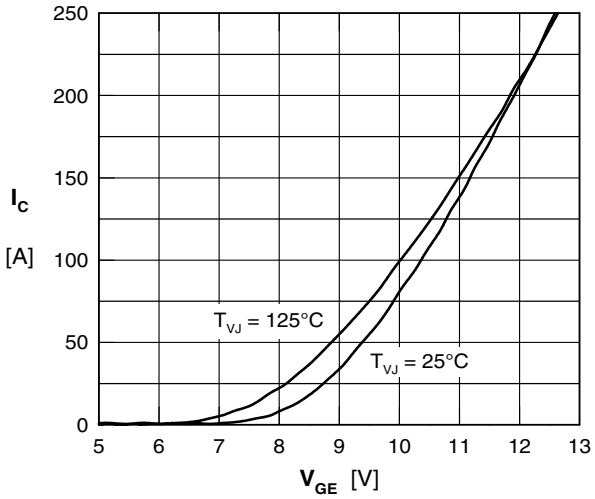


Fig. 3 Typ. transfer characteristics

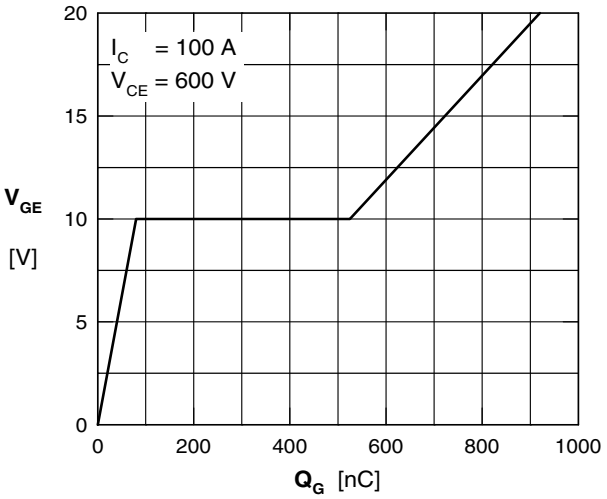


Fig. 4 Typ. turn-on gate charge

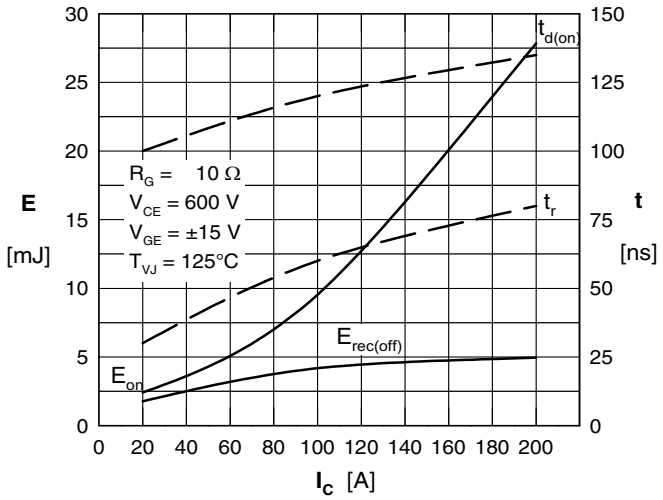


Fig. 5 Typ. turn-on energy & switching times versus collector current

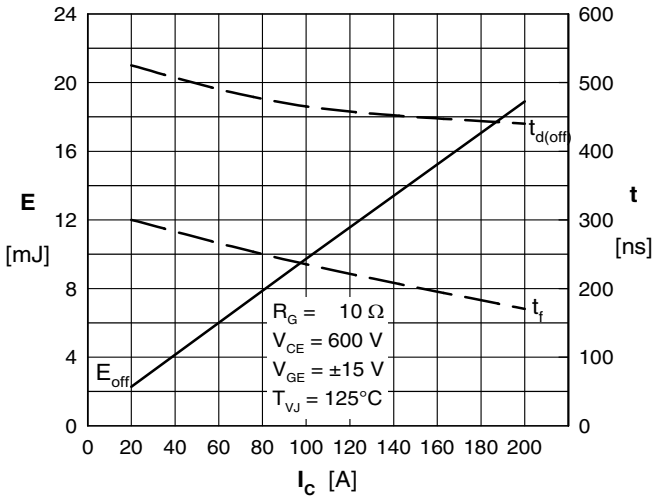


Fig. 6 Typ. turn-off energy & switching times versus collector current

Transistor T1 - T4

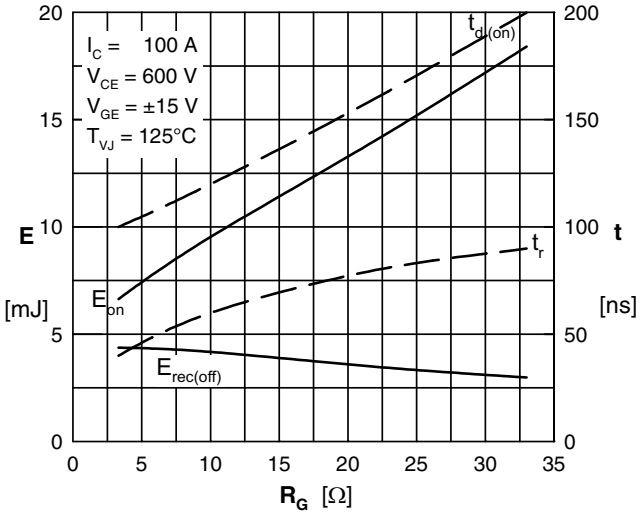


Fig. 7 Typ. turn-on energy and switching times versus gate resistor

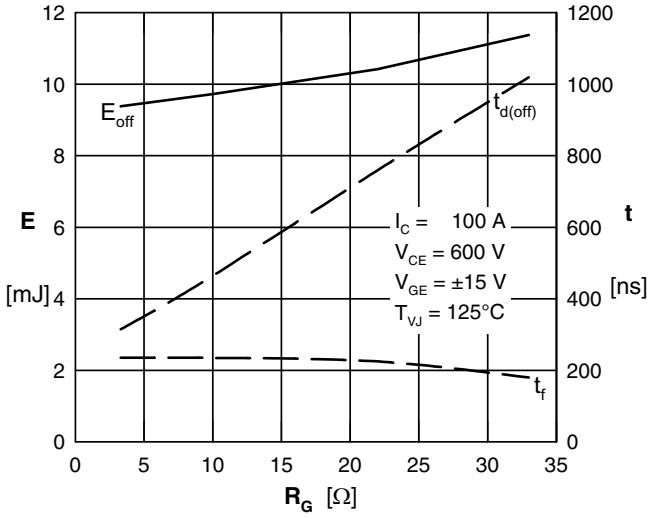


Fig. 8 Typ. turn-off energy and switching times versus gate resistor

Diode D1 - D4

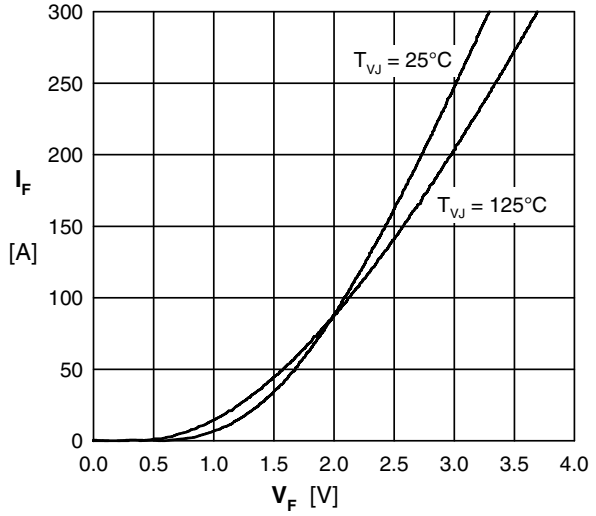


Fig. 9 Typ. forward characteristics

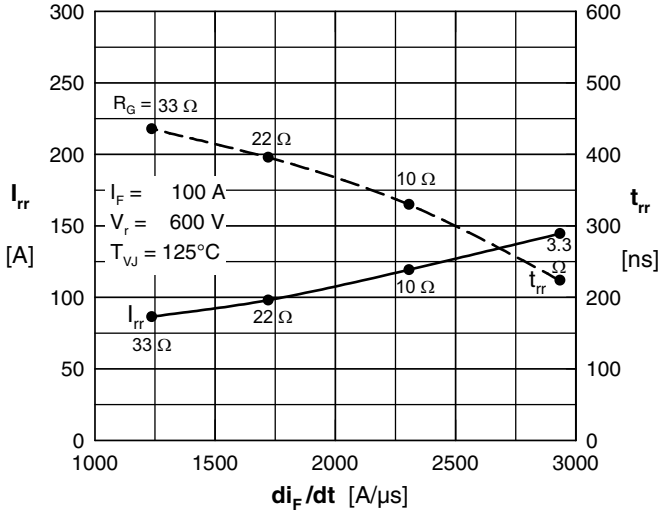


Fig. 10 Typ. reverse recovery characteristics

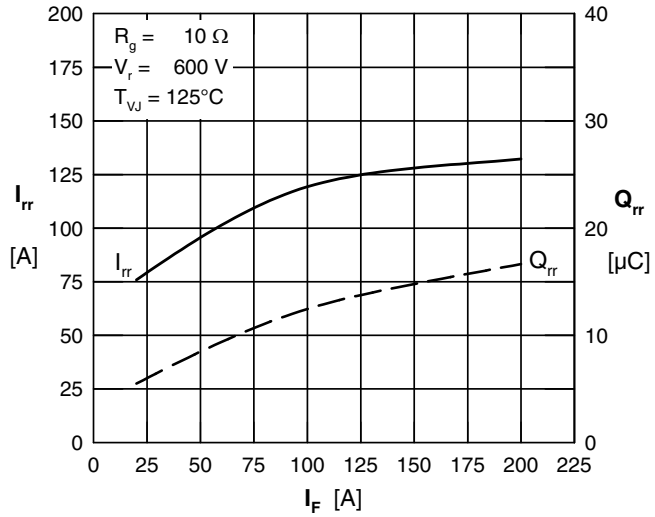


Fig. 11 Typ. reverse recovery characteristics

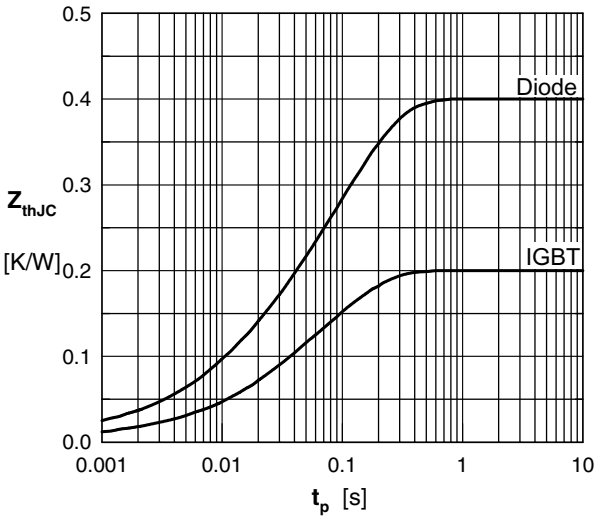


Fig. 12 Typ. transient thermal impedance

IGBT		FRD	
R_i	τ_i	R_i	τ_i
0.003	0.00001	0.015	0.0005
0.010	0.0014	0.04	0.006
0.057	0.021	0.09	0.025
0.130	0.1	0.255	0.125

Fig. 13 Thermal coefficients

Diode D1 - D4

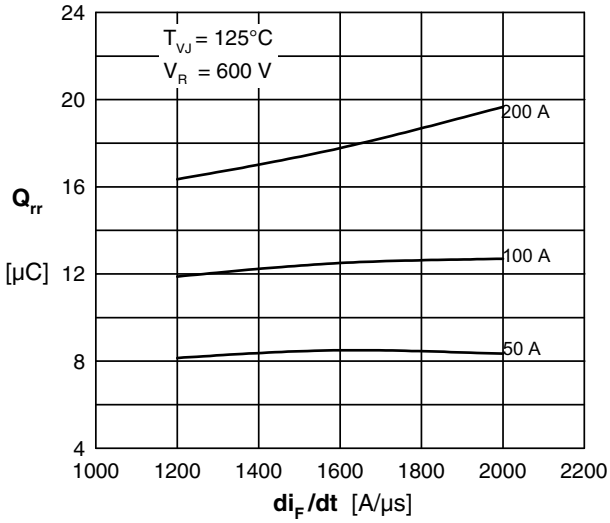


Fig. 14 Typ. reverse recov.charge Q_{rr} vs. di/dt

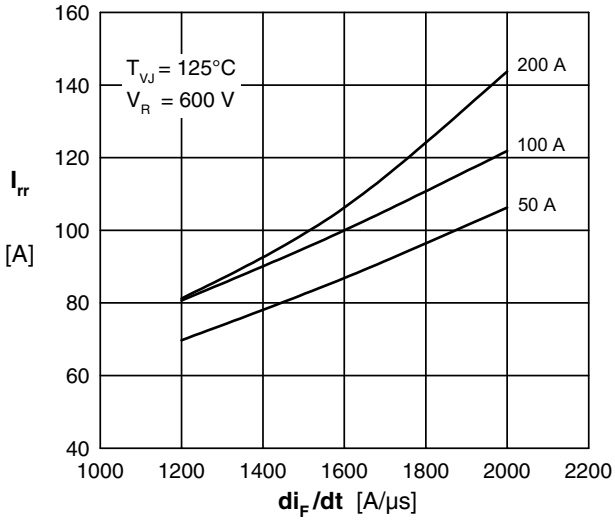


Fig. 15 Typ. peak reverse current I_{RM} vs. di/dt

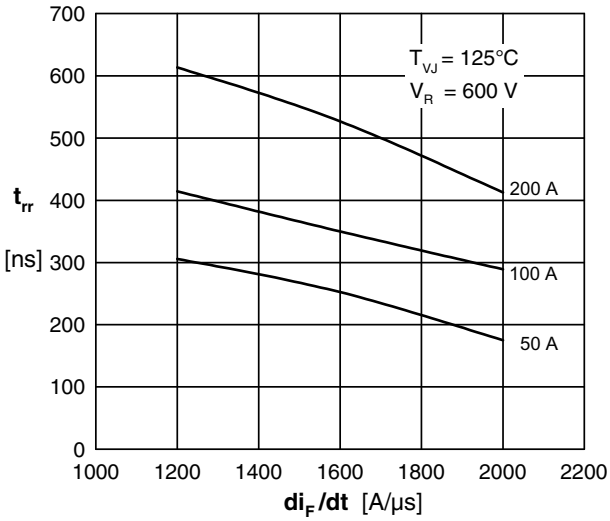


Fig. 16 Typ. recovery time t_{rr} versus di/dt

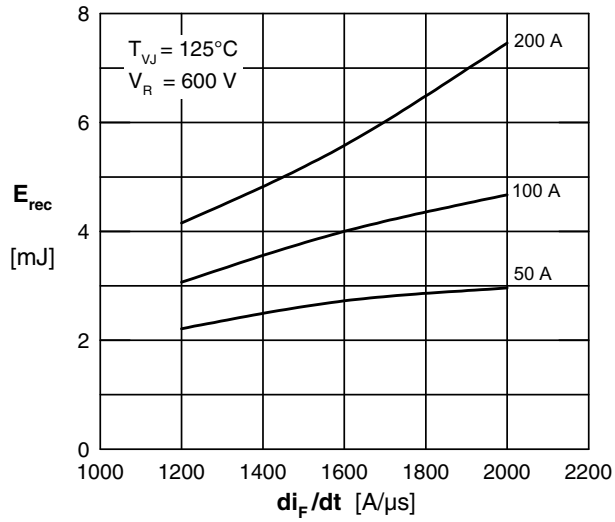


Fig. 17 Typ. recovery energy E_{rec} versus di/dt